

13. A mould for encapsulating electronic components mounted on a carrier, comprising:

at least two mould parts displaceable relative to each other, at least one of which is provided with a recess, and

5 feed means for encapsulating material,

wherein at least one of the mould parts is provided with a runner which connects on one side to a wall of a mould part co-defining a mould cavity and connects on the other side to a side of the mould part remote from the mould cavity,

wherein the runner takes a multiple form that connects to a number of apertures  
10 in the wall of a lower mould part on positions opposite the recess in the upper mould part.

A 4 14. The mould as claimed in claim 13, wherein a plurality of runners connecting onto the wall defining the mould cavity is in mutual communication and is connected to a single runner which connects onto a side of the lower mould part remote from the mould cavity.

15. The mould as claimed in claim 13, wherein the runner debouches in a wall defining a mould cavity, which wall is screened from a feed opening for encapsulating material by a carrier when encapsulating material is fed to the mould.

16. The mould as claimed in claim 13, wherein the apertures are arranged in the wall of a lower mould part in patterns.

17. The mould as claimed in claim 13, wherein the lower mould part is provided with at least one aligning edge for positioning a carrier relative to the lower mould part.

18. An encapsulating device for encapsulating electronic components mounted on a carrier, comprising:

a mould as claimed in claim 13,

drive means for positioning and causing the mould parts to move relative to each

5 other,

feed means for encapsulating material, and

a fan connecting onto the side of the runner remote from the mould cavity, wherein the fan is adapted to blow gases into the runner and to extract gases from the runner.

19. A method for encapsulating electronic components mounted on a carrier, using a mould defining a mould cavity and a runner connecting onto a wall co-defining the mould cavity, comprising the steps of:

A) positioning at least one carrier relative to a lower mould part,

5 B) closing the mould by moving the lower mould part and an upper mould part towards each other,

C) feeding encapsulating material to the part of the mould cavity left clear by the carrier, and

D) opening the upper and lower mould parts and removing the carrier with  
10 encapsulating material arranged thereon, wherein during step D) an overpressure is applied in the runner which overpressure releases the encapsulated electronic components from the lower mould part.

20. The method for encapsulating electronic components according to claim 19, wherein after step A) during step B) an underpressure is applied in the runner, whereby the carrier is sucked to the lower mould part.